## Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

## Listing of Claims:

Claim 1 (original): A semiconductor light emitting device comprising a metallic support plate; a light-reflective reflector mounted on the support plate and formed with a hole upwardly diverging; a semiconductor light emitting element mounted on the support plate within the hole of the reflector, the light emitting element having a first electrode electrically connected to the support plate; a first wiring conductor electrically connected to the support plate; a second wiring conductor electrically connected to a second electrode of the light emitting element; and a heat-resistible plastic encapsulant for sealing at least an outer periphery of the reflector, an upper surface of the support plate, each inner end of the first and second wiring conductors.

Claim 2 (original): The semiconductor light emitting device of claim 1, further comprising a lens formed of light-tansmittable or transparent resin for covering upper surfaces of the reflector and plastic encapsulant.

Claim 3 (previously presented) The semiconductor light emitting device of claim 2, further comprising a light-tansmittable or transparent cover for covering a hole of the reflector.

Claim 4 (previously presented) The semiconductor light emitting device of claim 1, wherein the support plate is formed of a metallic material having the thermal conductivity equal to or

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more than 190 kcal/mh°C.

Claim 5 (previously presented) The semiconductor light emitting device of claim 1, wherein the lens is formed of a resin which has the melting point lower than that of the plastic encapsulant.

6-12 (canceled).

Claim 13 (original): A semiconductor light emitting device comprising a support plate; a light-reflective reflector mounted on the support plate and formed with a hole upwardly diverging; and a semiconductor light emitting element mounted on the support plate within the hole of the reflector;

wherein the reflector has a ledge connected to a wiring conductor to electrically connect the light emitting element and wiring conductor through the ledge.

Claim 14 (original): The semiconductor light emitting device of claim 13, wherein the ledge is electrically connected to the wiring conductor via brazing metal.

Claim 15 (previously presented) The semiconductor light emitting device of claim 13, wherein a lead wire electrically connects the semiconductor light emitting element and a flat area formed in the reflector.

Claim 16 (original): A reflector for a semiconductor light emitting device, comprising:

a reflector block mounted on a support plate and formed with a hole for defining a reflective surface upwardly expanding, the reflector block surrounding a semiconductor light

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emitting element for upwardly reflecting light from the semiconductor light emitting element;

a notch extending through the reflector block from the hole to an outer side surface between the semiconductor light emitting element and wiring conductor; and

a lead wire passing through the notch for electrically connecting the semiconductor light emitting element and wiring conductor.

Claim 17 (original): The reflector of claim 16, further comprising a filler received in the notch through which the lead wire extends.

Claim 18 (original): The reflector of claim 17, wherein the filler forms a part of the reflector.

Claim 19 (original): A semiconductor light emitting device comprising a support plate; a light-reflective reflector having a reflector block which is mounted on the support plate or integrally formed with the support plate, the reflector being formed with a hole upwardly expanding; a semiconductor light emitting element mounted on the support plate within the hole of the reflector; a first wiring conductor electrically connected to one electrode of the light emitting element; a second wiring conductor electrically connected to the other electrode of the light emitting element through a lead wire; and a plastic encapsulant for sealing at least the hole of the reflector;

wherein the reflector has a notch which passes through the reflector block between the hole and an outer side wall and between the light emitting element and wiring conductor;

the lead wire passes through the notch to electrically connect the light emitting element and wiring conductor.

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20. (canceled).